PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/15230
1.3 Title of PCN	SAMSUNG Foundry (South Korea) additional source for STM32H74x & STM32H75x listed products
1.4 Product Category	STM32H742x, STM32H743x, STM32H745, STM32H747x, STM32H750x, STM32H753x, STM32H755x, and STM32H757x.
1.5 Issue date	2026-05-29

2. PCN Team	
2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication (SOP 2617)	ST Crolles (France) HHGrace Wuxi (China) SAMSUNG Foundry (South Korea)

4. Description of change		
	Old	New
4.1 Description	Front-end source: - ST Crolles 12" (France) - HHGrace Wuxi (China)	Front-end sources: - ST Crolles 12" (France) - HHGrace Wuxi (China) - SAMSUNG Foundry 12" (South Korea) - added source There is no change in the product functionality. Please refer to PCN – Additional information attached document.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Packaged products : no change.	

5. Reason / motivation for change	
5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose & Automotive Microcontroller division decided to qualify an additional front-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change	
6.1 Description	Change is visible through diffusion traceability plant, on the marking: - “VQ” for ST Crolles 12" (France) - "Y5" for HHGrace FAB7 (China) - "2E" for HHGrace FAB9 (China) - “LM” for SAMSUNG 12" (South Korea)

7. Timing / schedule	
7.1 Date of qualification results	2026-05-05
7.2 Intended start of delivery	2026-09-01
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	15230 MDG-GPM-RER2403_PCN15230 V1_450-transfer-to-SF - reliability evaluation report.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2026-05-29

9. Attachments (additional documentations)
15230 Public product.pdf 15230 MDG-GPM-RER2403_PCN15230 V1_450-transfer-to-SF - reliability evaluation report.pdf 15230 _Additional information.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32H743VIT6	
	STM32H743VIT6TR	
	STM32H745XIH3	
	STM32H750IBK6	
	STM32H750IBK6TR	
	STM32H750VBT6	
	STM32H750VBT6TR	

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